

**Amendments to the Specification**

***Please replace the title with the following amended title:***

TRANSFER MOLDING [APPARATUS AND] METHOD FOR MANUFACTURING  
SEMICONDUCTOR DEVICES

**Please replace the CROSS REFERENCE TO RELATED APPLICATIONS  
section on page 1, between the title and the heading "BACKGROUND OF THE  
INVENTION" with the following section:**

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**CROSS REFERENCE TO RELATED APPLICATIONS**

**C** This is a divisional application of application Serial No. 09/265,841, filed March  
10, 1999, now U.S. Patent No. 6,267,577, which is hereby incorporated by reference in  
its entirety for all purposes.

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